



## The Advanced Application of Intelligent Sensor & Artificial intelligence (AI)

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### Message from the Guest Editors

Artificial intelligence (AI) has facilitated the development of human society. Its use in practice in recent years has proven the effectiveness of this technology for solving varieties of problems in industry, manufacturing, the medical field, etc. Indeed, in the last few decades, we have witnessed remarkable progress in sensor manufacturing and application. Applying artificial intelligence technology into sensors can make hardware systems more intelligent, thus accelerating the progress of practical application. Therefore, there is a pressing demand for new scalable and highly performing approaches that can cope with this explosion in the field of intelligent sensors and artificial intelligence (AI). We believe this Special Issue will serve as a timely collection of research on advantaged applications of intelligent sensors and artificial intelligence (AI).

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## Message from the Editor-in-Chief

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